

Amendments to the Claims

1. (Currently amended) A method for patterning a device layer using a patterned stamp, comprising the steps of:

(a) providing a substrate;

(b) bringing the patterned stamp into contact with the substrate so that the surface energy of the substrate is modified in accordance with the pattern of the stamp;

(c) removing the patterned stamp from the substrate; and

(d) depositing a solution of a device layer on the substrate after the patterned stamp has been removed; whereby the surface energy of the substrate determines the deposition pattern of the device layer, and

~~wherein step (b) is carried out so that the surface energy of the substrate is modified in accordance with the pattern,~~

wherein the topography of the surface of the substrate is unchanged after the patterned stamp has been brought into contact with the substrate.

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Previously presented) A method according to claim 1, comprising depositing the device layer by spin coating or inkjet printing.

6. (Previously presented) A method according to, claim 1, wherein the solvent is selected from the group consisting of xylene, ortho-xylene, toluene, benzene, mesitylene, chloroform, dichloromethane, and mixtures thereof.

7. (Canceled)

8. (Currently amended) A method according to claim 1, wherein ~~in step (b)~~ the surface energy in step (b) of any portion of the surface of the substrate that is in contact with the pattern stamp is modified.

9. (Original) A method according to claim 8, wherein the substrate comprises a polymer.

10. (Original) A method according to claim 9, wherein the polymer is poly (3,4-ethylenedioxythiophene) or polyaniline.

11. (Previously presented) A method according to claim 8, wherein the substrate is charged.

12. (Canceled)

13. (Currently amended) A method ~~according to any one of claims 1 to 7~~ for patterning a device layer using a patterned stamp, comprising the steps of:

(a) providing a substrate;

(b) bringing the patterned stamp into contact with the substrate so that the surface energy of the substrate is modified in accordance with the pattern of the stamp;

(c) removing the patterned stamp from the substrate; and

(d) depositing a solution of a device layer on the substrate after the patterned stamp has been removed; whereby the surface energy of the substrate determines the deposition pattern of the device layer.

wherein the patterned stamp is used as a mask in step (b) and step (b) includes subjecting any portion of the surface of the substrate that is not in contact with the patterned stamp to a surface energy modifying process.

14. (Original) A method according to claim 13, wherein the surface energy modifying process includes a step of exposing any portion of the surface of the substrate that is not in contact with the patterned stamp to UV radiation.

Claims 15.-23. (Canceled)